

Product Change Notification - KSRA-30MKCM076

Date:

26 Jun 2018

Product Category:

Interface- Controller Area Network (CAN); Linear Op Amps; Power MOSFET Drivers; Switching Regulators; Memory

Affected CPNs:



Notification subject:

CCB 3269 Final Notice: Qualification of 8600 die attach and G700LTD mold compound for selected products available in 8L TDFN package at NSEB assembly site.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of 8600 die attach and G700LTD mold compound for selected products available in 8L TDFN package at NSEB assembly site.

Pre Change:

Using 8200T die attach material and G770HCD molding compound material

Post Change:

Using 8200T or 8600 die attach material and G770HCD or G700LTD molding compound material

Pre and Post Change Summary:

_	Pre Change	Post Change					
Accombly Site	UTAC Thai Limited	UTAC Thai Limited	UTAC Thai Limited				
Assembly Site	LTD. / NSEB	LTD. / NSEB	LTD. / NSEB				
Wire material	Au wire	Au wire	Au wire				
Die attach material	8200T	8200T	8600				
Molding compound material	G770HCD	G770HCD	G700LTD				
Lead frame material	C194	C194	C194				

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying G770HCD mold compound and 8600 die attach material.

Change Implementation Status:

In Progress

Estimated First Ship Date:

July 26, 2018 (date code: 1830)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:



		January 2018				June 2018				July 2018						
Workweek	01	02	03	04	05	() <mark>□ ◇</mark> ◎ 중 () 달	22	23	24	25	26	27	28	29	30	31
Initial PCN Issue Date				X												
Qual Report											Х					
Availability											^					
Final PCN Issue Date											Χ					
Estimated															Χ	
Implementation Date																

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report

Revision History:

February 12, 2018: Issued initial notification.

June 26, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on July 26, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachment(s):

PCN KSRA-30MKCM076 Qual Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

24AA00T-I/MNY

24AA128T-I/MNY

24AA256T-E/MNY

24AA256T-I/MNY

24C00T-E/MNY

24C00T-I/MNY

24FC128T-I/MNY

24FC256T-I/MNY

24LC00T-I/MNY

24LC128T-E/MNY

24LC128T-I/MNY

24LC256T-E/MNY

24LC256T-I/MNY

MCP14A0153T-E/MNY

MCP14A0154T-E/MNY

MCP14A0155T-E/MNY

MCP14A0453-E/MNY

MCP14A0453T-E/MNY

MCP14A0454-E/MNY

MCP14A0454T-E/MNY

MCP14A0455-E/MNY

MCP14A0455T-E/MNY

MCP14A0601T-E/MNY

MCP14A0602T-E/MNY

MCP16251T-I/MNY

MCP16252T-I/MNY

MCP16311T-E/MNY

MCP16312T-E/MNY

MCP16331T-E/MNY

MCP1661T-E/MNY

MCP1662T-E/MNY

MCP1663T-E/MNY

MCP1664T-E/MNY

MCP2542FDT-E/MNY

MCP2542FDT-H/MNY

MCP2542WFDT-E/MNY

MCP2542WFDT-H/MNY

MCP2544FDT-E/MNY

MCP2544FDT-H/MNY

MCP2544WFDT-E/MNY

MCP2544WFDT-H/MNY

MCP2557FDT-H/MNY

MCP2558FDT-H/MNY

MCP621T-E/MNY

MCP631T-E/MNY

MCP651T-E/MNY

Date: Monday, June 25, 2018

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M	P661T-E/MNY
	P6H01T-E/MNY
	P6H02T-E/MNY
	P6H71T-E/MNY
	P6H81T-E/MNY
	P6H82T-E/MNY
	P6H91T-E/MNY
	P6H92T-E/MNY
	P6V01T-E/MNY
	P6V03T-E/MNY
	P6V06T-E/MNY
	P6V08T-E/MNY
	P6V26T-E/MNY
	P6V28T-E/MNY
14.	

Date: Monday, June 25, 2018